

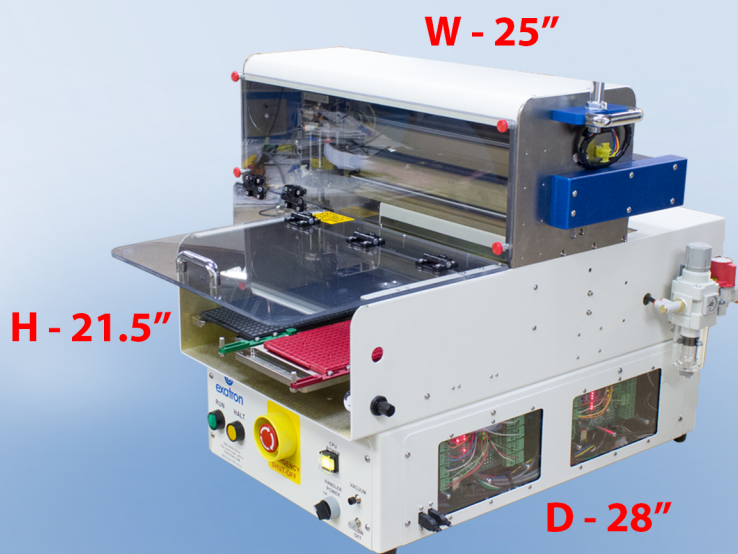
MODEL 802 TABLE TOP

VERSATILE, ECONOMICAL SINGLE SITE TEST HANDLER



- 1,000 UPH (units per hour) as shown.
- Two JEDEC trays.
- Handles all SMD and leaded device types from 1.6 x 1.6mm to 60 x 60mm.
- Near zero mechanical adjustments or changeover kits.
- Bottom-side calibration camera ensures precise alignment.
- Servo motor-driven device placement.
- User-friendly Windows 7-based GUI.
- Designed and manufactured in the USA.

*Full test functionality
in a powerful
small package*



2842 Alello Drive, San Jose, CA 95111
1-800-EXA-TRON 1-408-629-7600 www.exatron.com

exatron MODEL 802 TABLE TOP

SPECIFICATIONS, FEATURES, AND OPTIONS

Specifications:

Size:	63.5cm W x 71cm D x 55cm H (25" W x 28" D x 21.5" H) (excludes light pole) (With standard 24" gantry. 30" gantry optional)
Weight:	Under 45Kg (under 100 lbs.)
Power:	120 VAC 60 Hz or 220 VAC 50/60 Hz
Air:	5.5 bar (80 PSI) - 2 CFM clean, dry air
Operational Temperature:	13-32°C (55-90°F)
Humidity:	30-45% RH non-condensing (required for cold test)

Positioning System:

X-Y Drive System:	Servo motor-driven lead screws
X-Y Axis Resolution:	0.1mm (0.003")
X-Y Axis Max. Velocity:	122cm/s (48"/s) (High speed gantry optional)
Z Plunger:	Servo motor-driven lead screw
Z Axis Resolution:	+/- 0.1mm (0.003")
Z Axis Repeatability:	+/- 0.1mm (0.003")
Theta Drive System (optional):	Precision stepper motor
Theta Axis Resolution:	0.1°
Theta Axis Repeatability:	+/- 0.1mm (0.003")

802 Table Top Features:

Device types:	BGA, CSP, DIP, Flat Pack, LCC, LGA, MSOP, PCB, PGA, PLCC, QFP, SIMM, SIP, SIMM, SODIMM, SOIC, SSOIC, TSSOP, and custom.
Test site:	Single site standard. Dual sites available.
Test sockets:	Supports nearly all OEM test sockets; Exatron custom-built spring probe sockets; and Exatron Particle Interconnect (PI) RF & CSP
DUT board:	8" clearance under board; up to 12" x 12" square with centered socket; many mounting options.
Contact Force:	0-20 lbs standard, software controlled.
Test Interface:	RS-232, Ethernet
Jam rate:	1/5000 when using Exatron test sockets.
Tray:	Fits all formats of JEDEC tray, 2" and 4" waffle packs.
Binning:	Up to 8 sorts standard, output tray sort mapping; drop to bucket standard.
Double part protection:	Standard built-in vacuum sensor checks for empty socket at start of job and before each pick and place.
Precisor:	Mechanical precisor ready; built-in controls for many precisor options.
Changeover:	Nearly kit-less - change pick up tip (if needed) change test socket, load new trays, load previously set up JOB file. All mechanical changeover adjustments software-controlled.

Options:

TEMPERATURE UPGRADES:

Single temp. test site (requires 30" gantry)
(-75°C) -55°C to +155°C (+175°C) test capability.

VISION UPGRADES: (May require longer gantry)

Top-side OCR camera
Bottom-side 2D and 3D lead inspection (requires table option)

TEST INTERFACE OPTIONS:

TTL/opto isolated
GPIB

MEDIA UPGRADES: (May require longer gantry)

Detaper input
Exatron-built tape and reel output
Small volume tube to tube
Bucket output

MARKING UPGRADES:

In-tray laser marking



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